

**Amendments to the Specification**

Please replace the paragraph beginning on page 6, line 22, with the following rewritten paragraph:

According to this electronic module, the power supply interconnects are formed extending through a pair of regions located on both sides of the EL section and the integrated circuit chip. ~~Therefore, current can be allowed to uniformly flow through both sides of the EL section. Therefore, current can be allowed to equivalently flow on both sides of the EL section due to equivalence of impedance of the power supply interconnects on the both sides, lowering the impedance to diminish noise.~~

Please replace the paragraph beginning on page 8, line 7, with the following rewritten paragraph:

According to this method of manufacturing an electronic module, the power supply interconnects are formed extending through a pair of regions located on both sides of the EL section and the integrated circuit chip. ~~Therefore, current can be allowed to uniformly flow through both sides of the EL section. Therefore, current can be allowed to equivalently flow on both sides of the EL section due to equivalence of impedance of the power supply interconnects on the both sides, lowering the impedance to diminish noise.~~